

SPECIFICATION FOR TFT+TP MODULE

MODEL NO:	TM070RVZ06
CUSTOMER:	
CUSTOMER P/N.	
VERSION	V0.1
CUSTOMER	
APPROVED	

■Prelimina	ry specification
□Final spe	cification

PREPARED BY	CHECKED BY	VERIFIED BY QA DEPT.	APPROVED BY

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TFT+TP REVISION RECORD

Version	Page	Revision Items	Name	Date
0.1		First release	JIM	2013.02.25



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1 General Specifications

TM070RVZ06 is a color active matrix LCD module incorporating amorphous silicon TFT (Thin Film Transistor). It is composed of a color TFT-LCD panel, driver IC with CABC function, FPC, a back light unit and CTP (Capacitive Touch Panel) with Multi-Touch function. The mounting method is with optical bonding . This product accords with RoHS environmental criterion.

Item	Feature	Spec	Unit	Note
	Size	7	inch	
	Resolution	800(RGB) x 480		
	Interface	RGB 24 bits		
	Color Depth 16.7M			
	Technology Type	a-Si		
	Pixel Pitch	0.1926x0.179	mm	
TFT	Pixel Configuration	R.G.B. Vertical Stripe		
	Display Mode	TM with Normally White		
	Surface Treatment(Up Polarizer)	Anti-Glare(3H)		
	Viewing Direction	12 o'clock		1
	Gray Scale Inversion Direction	6 o'clock		
	LCM (W x H x D)	171.50x110.30x7.35	mm	
	Operation Technology	Projected capacitive		
	Control IC	NT11003		
	Input Method	Bare finger		
	Number of simultaneous touches	2 points		
TP	Surface hardness			
	Minimum Touch Area	Ф6	mm	
	Finger Pitch	13	mm	
	Product structure	Glass Lens – Glass Sensor		2
	Interface	12C		
	TFT Active Area	157.00x92.8	mm	
 Mechanical	TP Active Area	155.24(W) x 87.12(H)	mm	
Characteristics	LED Numbers	24 LEDs		
	Weight		g	



Reliability	Operation temperature	-20~70	$^{\circ}\mathbb{C}$	
Characteristics	Storage temperature	-30~80	$^{\circ}\mathbb{C}$	

Note 1: Viewing direction for best image quality is different from Gray Scale Inversion Direction, there is a 180 degree shift.

Note 2: Requirements on Environmental Protection: RoHS



2. Input/Output Terminals

2.1 TFT CN1 pin assignment

Connector type: FH28-60S-0.5SH

PIN	Symbol	I/O	Description	Remark
1	VLED+	Р	Led anode	
2	VLED+	Р	Led anode	
3	VLED-	Р	Led cathode	
4	VLED-	Р	Led cathode	
5	GND	Р	Ground	
6	VCOM	Р	Common voltage input	
7	VCC	Р	Digital power supply	· ·
8	MODE	-	DE/SYNC mode select. H:DE mode, L:SYNC mode	
9	DE	Ι	Data enable signal, active high to enable data,if not used,please pull low	
10	VSYNC	Ι	Vertical sync input, negative polarity,if not used,please pull High	
11	HSYNC	I	Horizontal sync input, negative polarity,if not used,please pull High	
12	B7	Ι	Blue data (MSB)	
13	B6	Ι	Blue data	
14	B5	I	Blue data	
15	B4	Ι	Blue data	
16	B3	Ι	Blue data	
17	B2	Ι	Blue data	
18	B1	Ι	Blue data	
19	B0	1	Blue data (LSB)	
20	G7	Ι	Green data (MSB)	
21	G6	Ι	Green data	
22	G5	I	Green data	
23	G4		Green data	
24	G3		Green data	
25	G2		Green data	
26	G1		Green data	
27 (G0	-	Green data (LSB)	
28	R7	I	Red data (MSB)	
29	R6	Ι	Red data	
30	R5	Ι	Red data	
31	R4	Ι	Red data	
32	R3	Ι	Red data	
33	R2	1	Red data	
34	R1	1	Red data	
35	R0	I	Red data (LSB)	
36	GND	Р	Ground	
37	DCLK	Ι	Clock for input data	
38	GND	Р	Ground	
39	LR	Ι	Source left or right sequence control	



40	UD	I	Gate up or down scan control
41	VGH	Р	Positive power of TFT
42	VGL	Р	Negative power of TFT
43	AVDD	Р	Analog power supply
44	RESET	Ι	Global reset pin
45	NC	NC	
46	VCOM	Р	Common voltage input
47	DITHB	1	Dithering setting. H: 6bit resolution, L: 8bit resolution
48	GND	Р	Ground
49	NC	NC	
50	NC	NC	

Note1: I/O definition.

I---Input, O---Output, P--- Power/Ground, N--- No connection

Note2:

Scan con	trol input	Seepping direction
UD	LR	Scanning direction
GND	VCC	Up to down, left to right
VCC	GND	Down to up, right to left
GND	GND	Up to down, right to left
VCC	VCC	Down to up, left to right

2.2 TP pin assignment

Pin No.	Symbol	1/0	Description	Remark
1	SCL	I	I2C clock input	
2	SDA	I/O	I2C data input and output	
3	GND	Р	Groud	
4	GND	Р	Groud	
5	ATTN	I/O	External interrupt to the host	
6	GND	Р	Groud	
7	VPP	I/O	External interrupt from the host	
8	VDD	Р	CTP power supply	
9	GND	Р	Groud	
10	GND	Р	Groud	



3. Absolute Maximum Ratings

Ta = 25℃

Item	Symbol	Min	Max	Unit	Remark
	VDD	-0.50	5.00	V	
	AVDD	-0.50	15.00	V	
Power Voltage	VGH	-0.30	42.00	V	
	VGL	-20.0	0.30	V	
	VGH-VGL	-0.30	40.00	V	
Backlight Forward Current	ILED	-	200	mA	
Operating Temperature	TOPR	-20	70	$^{\circ}$	Note2
Storage Temperature	TSTG	-30	80	$^{\circ}\mathbb{C}$	

Table 3.1 absolute maximum rating

Note1: The parameter is for driver IC (gate driver, source driver) only

Note2: 80℃ is the surface temperature of module

4. Electrical Characteristics

4.1 .1Driving TFT LCD Panel

Ta = 25℃

							10 20 c
	Item	Symbol	Min	Тур	Max	Unit	Remark
Voltage for logic circuit		VCC	3.00	3.30	3.60	V	
Analog Supply Voltage		AVDD	9.88	10.4	10.92	V	
Gate On Voltage		VGG	14.4	16	17.6	V	
Gate O	ff Voltage	VEE	-7.70	-7.00	-6.30	V	
Commo Driving	on Electrode Signal	VCOM	3.68	3.70	3.72	V	
Input Signal	Low Level	VIL	0	-	0.3xVCC	V	
Voltag e	High Level	VIH	0.7xVCC	-	VCC	V	

Table 4.1 LCD module electrical characteristics

Note1: For different LCM, the value may have a bit of difference. Note2: To test the current dissipation, use "all Black Pattern".

4.1.2 TFT Driving Backlight

Item	Symbol	Condition	Min	Тур	Max	Unit	Remark
Forward Voltage	VLED	I _F =160mA		9.6	10.8	V	
Forward Current	l _F	-	-	160	200	mA	Note 1
Backlight Power Consumption	WBL	I _F =160mA		1536	2160	mW	
Life Time	-	I _F =160mA	10,000	-	-	Hrs	Note 3

Table 4.2 LED backlight characteristics

Note 1: IF is defined for one channel LED. There are total three LED channels in back light



unit. Under LCM operating, the stable forward current should be inputted.

Note 2: Optical performance should be evaluated at Ta=25°C only.

Note 3: If LED is driven by high current, high ambient temperature & humidity condition. The life time of LED will be reduced. Operating life means brightness goes down to 50% initial brightness. Typical operating life time is estimated data.

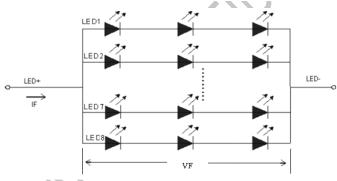


Figure 4.2 LED connection of backlight

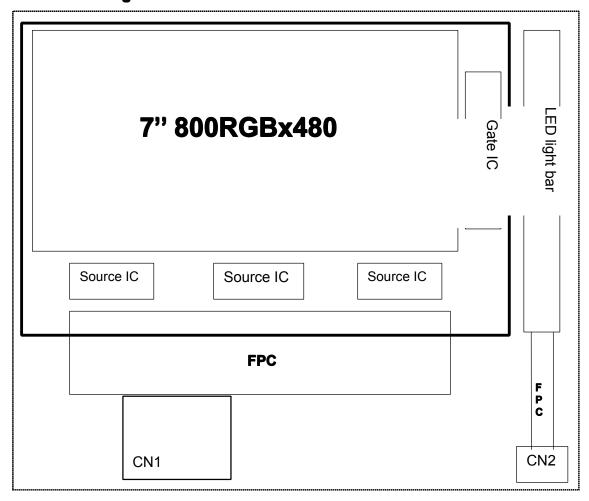
4.2 TP DC Characteristics

(T_A= 25°C, VDD=3.3V)

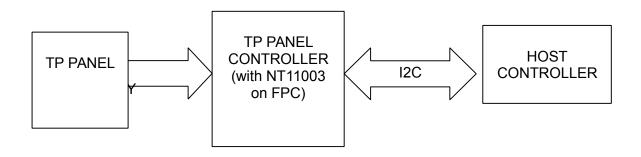
Item	Min	Тур	Max	Unit	Note		
power supply voltage	2.7	3.3	3.6	V	DC(noise should be under 100mV)		
Power supply current			10	mA			



4.3.1 TFT Block Diagram



4.3.2 TP Circuit Block Diagram





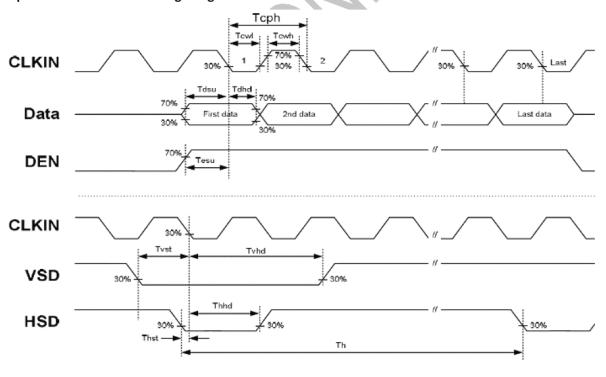
5. Timing Chart

5.1 TFT-LCD Input Timing

VCC=3.3V, GND=0V, Ta=25°C

Parameter	Symbol	Min	Тур	Max	Unit	Remark
DCLK frequency	Fclk	28	30.0	40.0	MHz	
DCLK cycle time	Tcph	25	33.3	36	ns	
DCLK pulse width	Tcw	40%	50%	60%	Tcph	
VS setup time	Tvst	8			ns	
VS hold time	Tvhd	8	-	-	ns	
HS setup time	Thst	8			ns	
HS hold time	Thhd	8	-	-	ns	
Data setup time	Tdsu	8			ns	Data to DCLK
Data hold time	Tdhd	8	-	-	ns	Data to DCLK
DE setup time	Tesu	8	-	-	ns	
DE hold time	Tehd	8		- ,	ns	/

Input Clock and Data timing Diagram:





5.2 Recommended Timing Setting Of TCON

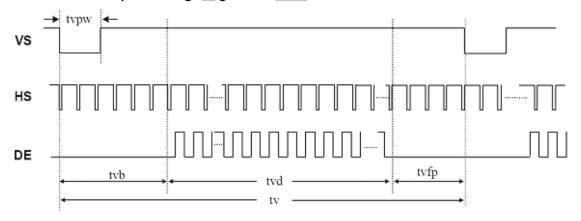
TCON (Embedded In Source IC) Input Timing (DCLK, HS, VS, DE)

VCC=3.3V, GND=0V, Ta=25°C

Parameter	Symbol	Min	Тур	Max	Unit	Remark
DCLK	Fclk	28	30	40	MHZ	
DCLK	tclk	20	33.3	36	ns	
	th	862	1056	1200	tclk	
	thd	800	800	800	tclk	
HSD	thpw	1	-	40	tclk	
	thb	46	46	46	tclk	
	thfp	16	210	354	tclk	
	tv	510	525	650	th	
	tvd	480	480	480	th	
VSD	tvpw	1	3	20	th	
	tvb	23	23	23	th	
	tvfp	7	22	147	th	

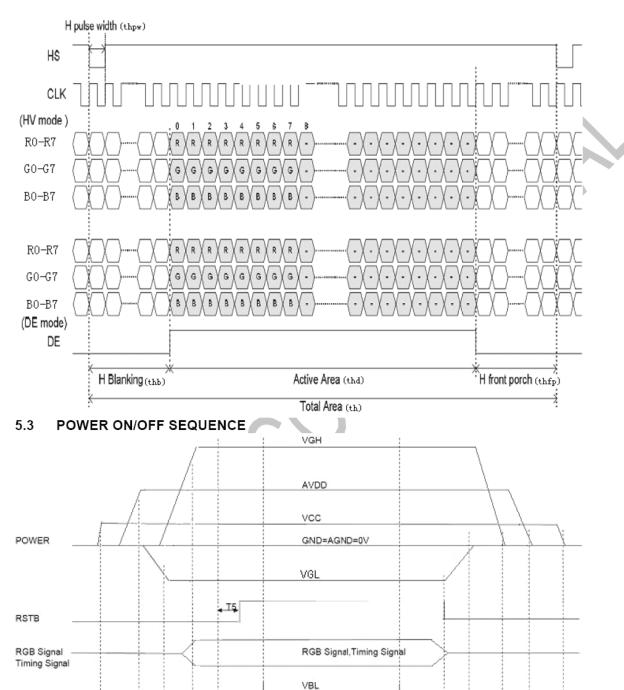
Note 1: DE timing refer to HS, VS input timing.

TCON Vertical Input Timing Diagram HV





TCON Horizontal Input Timing Diagram



Note 1: T1≥20ms, T2≥20ms, T3≥5ms, T4≥100ms, T5≥5ms.

Power ON Sequence

LED BLU

T2

Power OFF Sequence



6. Optical Characteristics

6.1 TFT Optical Characteristics

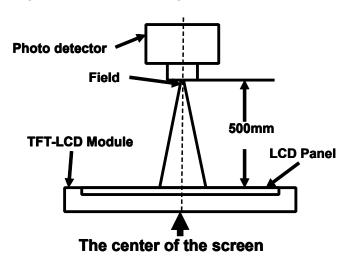
Item		Symbol	Condition	Min	Тур	Max	Unit	Remark	
		θТ		55	60				
Viou Anglos		θВ	CR≧10	65	70		Dograd	Note 2	
View Angles		θL	CR≡ IU	65	70		Degree	Note 2	
		θR		65	70				
Contrast Ratio		CR	θ=0°	400	500			Left/right 0° Top/bottom 5°	
Response Time		T _{ON}	25 ℃		20	30	ms	Note1 Note4	
	White	Х		0.265	0.315	0.365			
		У		0.280	0.330	0.380			
	Red	Х		0.541	0.591	0.641			
Chromaticity		у	Backlight is	0.300	0.350	0.390		Note5	
Chilomaticity	Green	Х	on	0.298	0.348	0.388		Note1	
	Green	у		0.521	0.571	0.621			
	Blue	Х		0.101	0.151	0.211			
	Diue	у		0.051	0.101	0.151			
Uniformity		υ			75		%	Note1、Note6	
NTSC					50		%		
Luminance		L		240	300		cd/m ²	Note7	

Test Conditions:

- 1. I_F = 20mA(one channel), the ambient temperature is 25°C.
- 2. The test systems refer to Note 1 and Note 2.

Note 1: Definition of optical measurement system.

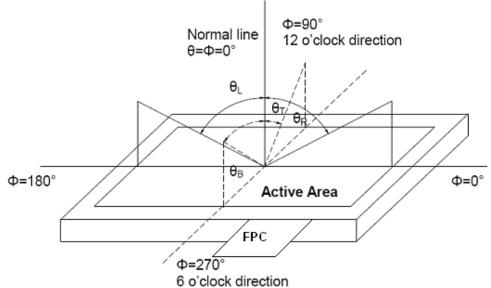
The optical characteristics should be measured in dark room. After 10 Minutes operation, the optical properties are measured at the center point of the LCD screen. All input terminals LCD panel must be ground when measuring the center area of the panel.



Item	Photo detector	Field
Contrast Ratio		
Luminance	CD 2A	1°
Chromaticity	SR-3A	!
Lum Uniformity		
Response Time	BM-7A	2°



Note 2: Definition of viewing angle range and measurement system. viewing angle is measured at the center point of the LCD by CONOSCOPE(ergo-80).



Note 3: Definition of contrast ratio

Contrast ratio (CR) = Luminance measured when LCD is on the "White" state

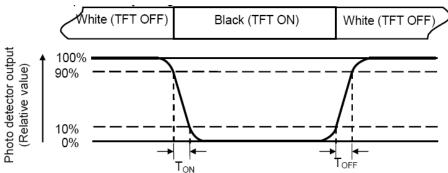
Luminance measured when LCD is on the "Black" state

"White state ": The state is that the LCD should drive by Vwhite. "Black state": The state is that the LCD should drive by Vblack.

Vwhite: To be determined Vblack: To be determined.

Note 4: Definition of Response time

The response time is defined as the LCD optical switching time interval between "White" state and "Black" state. Rise time (T_{ON}) is the time between photo detector output intensity changed from 90% to 10%. And fall time (T_{OFF}) is the time between photo detector output intensity changed from 10% to 90%.



Note 5: Definition of color chromaticity (CIE1931)

Color coordinates measured at center point of LCD.

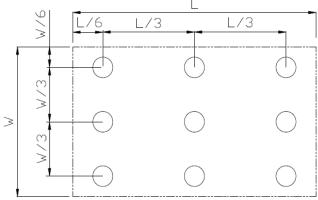
Note 6: Definition of Luminance Uniformity

Active area is divided into 9 measuring areas (Refer Fig. 2). Every measuring point is placed at the center of each measuring area.

Luminance Uniformity (U) = Lmin/Lmax

L-----Active area length W----- Active area width





Lmax: The measured Maximum luminance of all measurement position.

Lmin: The measured Minimum luminance of all measurement position.

Note 7: Definition of Luminance:

Measure the luminance of white state at center point.

6.2 TP Optical Characteristics

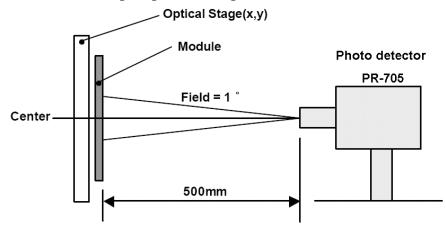
(Ta = 25 (C))

<u>(</u>	3 (0)					
No.	Item	Min.	Тур.	Max.	Unit	Remark
1	Transmission	86	88		%	Note 1
2	Reflectivity			4	%	Note 1,Note 2
3	HAZE			2	%	

Note1: Measuring equipments: DMS-501, PR-705. @550nm

Measuring condition:

- After stabilizing and leaving the panel alone at a given temperature for 30 min, the measurement should be executed,
 - Measuring surroundings: a stable, windless and dark room,
 - Measuring temperature: Ta=25°C,
 - 30 min after lighting the back-light.



Note2: conform to National standard GB2410—80 /ASTM D1003—61(1997)



7. Reliability Test

No	Test Item	Condition	Remarks
1	High Temperature Operation	Ta = +70℃, 240 hours	Note1,Note6,Note7 IEC60068-2-1,GB2423.2
2	Low Temperature Operation	Ta = -20℃, 240 hours	Note1, Note7,IEC60068-2-1 GB2423.1
3	High Temperature Storage	Ta = +80℃, 240 hours	Note1, Note7, Note8 IEC60068-2-1 GB2423.2
4	Low Temperature Storage	Ta = -30℃, 240 hours	Note1, Note7,EC60068-2-1 GB2423.1
5	High Temperature & Humidity Storage	Ta=+65°C 、RH=90%, 240 hours	Note1,Note3, Note4,Note7 IEC60068-2-78 GB/T2423.3
6	Thermal Shock/ Solder Joint Life Test	-30℃ (30min) ⇔80℃ (30min) ,Change Time:5min,100cycle	Note1,Note9 Start with cold temperature End with high temperature, IEC60068-2-14,GB2423.22
12	ESD	C=150pF \cdot R=330 Ω Air: \pm 8KV Contact: \pm 8KV 5times (Environment:15 $^{\circ}$ C ~35 $^{\circ}$ C, 30%~60%.86Kpa~106Kpa)	Note2,Note5, IEC61000-4-2 GB/T17626.2
13	Shock Test	Half Sine Wave 100G ,6ms,±X,±Y,±Z 3times for each direction	Note2
14	Drop Test(package state)	Height:60cm, 1corner,3edges,6surfaces	Note2,IEC60068-2-32 GB/T2423.8

Notes:

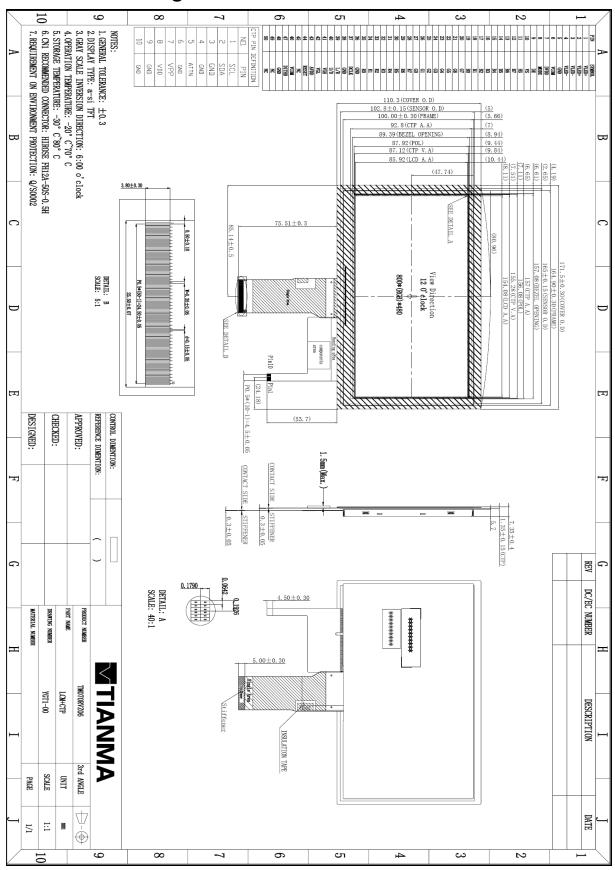
- 1. The test result shall be evaluated after the sample has been left at room temperature and humidity for 2 hours without load. No condensation shall be accepted. The sample will not be accepted if appear these defects:
- 1). Air bubble in the LCD;
- 2).Seal leak
- 3).Non-display
- 4).missing segments
- 5). Glass crack
- 6).CR reduction >40%
- 7).IDD increase >100%
- 8).Brightness reduction >50%
- 9).Color coordinate tolerance >0.05
- 2. The samples of these tests will not be accepted if appear these defects:
 - 1). Air bubble in the LCD;
 - 2).Seal leak



- 3). Non-display
- 4).missing segments
- 5). Glass crack
- 3. Each test item applies for a test sample only once, The test sample can not be used again in any other test item.
- 4.For Damp Proof Test, Pure water(Resistance $> 10M\Omega$) should be used.
- 5.In case of malfunction defect caused by ESD damage, if it would be recovered to normal state after resetting, it would be judge as a good part.
- 6 In the test of High Temperature Operation and High Temperature & Humidity Operation ,the operation temperature is the surface temperature of module
- 7 High Temperature Operation Low Temperature Operation High Temperature Storage Low Temperature Storage High Temperature & Humidity Operation High Temperature & Humidity Storage will be increased the test time to 1000hours in the same conditions to test out the ability of module, and we can not guarantee that the module will not fail during 1000hours. These items test only once
- 8. Thermal Shock will be changed the cycle to 1000cycles to test out the ability of module, and we can not guarantee that the module will not fail after the test. This item test only once



8 Mechanical Drawing





9. Product Inspection Criteria

9.1 Classification of defects

Major defects (MA): A major defect refers to a defect that may substantially degrade usability for product applications, including all functional defects(such as no display, abnormal display, open or missing segment, short circuit, missing component), outline dimension beyond the drawing, progressive defects and those affecting reliability.

Minor defects (MI): A minor defect refers to a defect which is not considered to be able to substantially degrade the product application or a defect that deviates from existing standards almost unrelated to the effective use of the product or its operation, such as black spot, white spot, bright spot, pinhole, black line, white line, contrast variation, glass defect, polarizer defect, etc.

9.2 Definition of inspection range

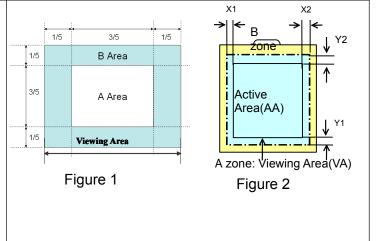
For dot defect of TFT LCD which is not smaller than 3 inches, dividing three areas to make a judgment (according to figure 1).

A area: center of viewing area
B area: periphery of viewing area
C area: Outside viewing area

For other defects, dividing two areas to make a judgment (according figure 2).

A zone : Inside Viewing area B zone : Outside Viewing area X1(A.A~V.A): 0mm X2(A.A~V.A): 0mm

Y1(A.A~V.A): 0mm Y2(A.A~V.A): 0mm



9.3 Inspection items and general notes

General	not specified in this standard happen, additional standard reement between customer and TIANMA. a which TIANMA guarantees. this Inspection standard.							
notes	4 Viewing judgment should be un5 Inspection conditions	der static pattern.						
	Inspection distance: 250 mm (fi	rom the sample) Temperature : 25±5 °C						
	Inspection angle : 45 degrees in 12 o'clock direction (all defects in viewing area should be inspected from this direction)							
	Pinhole, Bright spot, Black spot,	The color of a small area is different from the						
	White spot, Black line, White	remainder. The phenomenon doesn't change with						
	Line, Foreign particle, Bubble	voltage						
Inchastic	Contrast variation	The color of a small area is different from the remainder. The phenomenon changes with voltage						
Inspectio n items	Polarizer defect	Scratch, Dirt, Particle, Bubble on polarizer or between polarizer and glass						
	Dot defect (TFT LCD)	The pixel appears bright or dark abnormally when display						
	Functional defect	No display, Abnormal display, Open or missing segment, Short circuit, False viewing direction						

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Glass defect	Glass crack, Shaved corner of glass, Surplus glass
PCB defect	Components assembly defect

9.4 Outgoing Inspection level

Outgoing Inspection	Inspection conditions	Inspection							
standard	inspection conditions	Min.	Max.	Unit	IL	AQL			
Major Defects	See 9.3 general notes	See 9.5			II	0.65			
Minor Defects See 9.3 general notes		S	See 9.	5	II	1.5			
Note : Sampling standa	Note : Sampling standard conforms to GB2828								

9.5 Inspection Items and Criteria

				Judgment standard					
Inspection items			Category			Acceptable number			
			Category		A zone	B zone			
	Black spot, White spot, Bright Spot, Pinhole, Foreign Particle, Particle in or on glass, Scratch on glass	Φ=(a+b)/2(mm)	Α	4	0≦0.10	Neglected	Neglected		
			В	0.10)<Φ≦0.15	2			
1			С	0.15	5<Φ≦0.20	1			
			D	().20<Ф	0			
			То	Total defective point(B,C)		3			
	Black line, White line, and Particle Between Polarizer and glass, Scratch on glass	W:N Width L:Length(mm	Α	\ \	V≦0.01	Neglected			
2			В		<w≦0.03 L≦3.0</w≦0.03 	2			
			С		S <w≦0.05 L≦3.0</w≦0.05 	1	Neglected		
			D 0.05 <w< td=""><td>0</td><td rowspan="2"></td></w<>		0				
			Total defective point(B,C)		3				
	Contrast variation	b d d d d d d d d d d d d d d d d d d d	Α	(Ф≦0.2	Neglected			
			В	B 0.2<Φ≦0.3		2	Neglecte d		
3			С	C 0.3<Φ≦0.4		1			
			D	0.4<Ф		0			
			Total defe		ive point(B,C)	3			
4	Dot defect (if TFT LCD is			LCD Class Defect		A area	B area		
•			r LCD is		Α	Bright dot	1	Neglecte	

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	used)				Dark dot		2	d
	,				Total	2		
					Bright dot	2	2	
			В	В	Dark dot			
				Total	4			
		TFT LCD between 3~10.4 inches	1	LCD Class	Defect	A area	B area	C area
			A	Bright dot	1	1	Neglecte	
				Dark dot	1	2		
				Total	4	4		
					Bright dot	2	2	d
				В	Dark dot	2	3	
					Total	(3	
		Notes: Bright dot: in R · G · Dark dot: in R · G · E Defect area must be	3 or v	white dis	play figure, the	pixel app		
5	Bubble inside cell	l	any size			none		none
6	Polarizer defect (if Polarizer is used)	Scratch ,damage on polarizer, Particle on polarizer or between polarizer and glass.						
		Bubble, dent and convex	Α	·	Ф≦0.3	Negl	ected	Neglecte
			B 0.3		3<Φ≦0.7	2	2	d
			С		0.7<Ф	()	l u
	Surplus glass	Stage surplus glass	b≦0.3mm					
7		Surrounding surplus glass	Should not influence outline dimension and assembling					ssembling.
8	Open segment or	open common	Not permitted					
9	Short circuit		Not permitted					
10	False viewing direction		Not permitted					
11	Contrast ratio uneven		According to the limit specimen					
12	Crosstalk		According to the limit specimen					
13	Black /White spot(display)			Refer to item 1				
14	Black /White line(display)		Refer to item 2					



Inspection items			Judgment standard			
				Category(application: B zone)	Acceptabl e number	
	Glass defect crack	①The front of lead terminals b c	В	a≤ t, b≤1/5W, c≤3mm Crack at two sides of lead terminals should not cover patterns and alignment mark		
15		②Surrounding crack—non-contact side seal Inner border line of the Outer border line of the seal 3 Surrounding crack—contact side seal	c		Max.3 defects allowed	
		Inner border line of the Outer border line of the 4 Corner	В	$a \le t$, $b \le 3.0$, $c \le 3.0$ Glass crack should not cover patterns u and alignment mark and patterns.	_	



			1.1		
Inspection items			Judgment standard		
			Category(application: B zone)		
	PCB defect	Component soldering: No cold soldering short open circuit burr tin ball The flat encapsulation component position deviation must be less than 1/3 width of the pin (Pic.1); the sheet component deviation: Pin deviates from the pad and contact with the near components is not permitted (Pic.2)	Component Soldering pad Lead Component L1>0		
16		lead defect: The lead lack must be less than 1/3 of its width; The lead burr must be less than 1/3 of the seam; Impurities connect with the near leads is not permitted			
10		Connector soldering: Soldering tin is at contact position of the plug and socket is not permitted No foundation is scald Serious cave distortion on plug and socket contact pin is not permitted	Soldering tin is not permit in this area Soldering tin is not permit in this area Socket Base Board Base Board		
		Glue on root of the speaker receiver and motor lead: The insulative coat of the lead must join into the PCB; the protected glue must envelop to the insulative coat.	Glue Lead PCB Insulative coat		
			99		



10. Precautions for Use of LCD Modules

10.1 Handling Precautions

- 10.1.1 The display panel is made of glass. Do not subject it to a mechanical shock by dropping it from a high place, etc.
- 10.1.2 If the display panel is damaged and the liquid crystal substance inside it leaks out, be sure not to get any in your mouth, if the substance comes into contact with your skin or clothes, promptly wash it off using soap and water.
- 10.1.3 Do not apply excessive force to the display surface or the adjoining areas since this may cause the color tone to vary.
- 10.1.4 The polarizer covering the display surface of the LCD module is soft and easily scratched. Handle this polarizer carefully.
- 10.1.5 If the display surface is contaminated, breathe on the surface and gently wipe it with a soft dry cloth. If still not completely clear, moisten cloth with one of the following solvents:
 - Isopropyl alcohol
 - Ethyl alcohol

Solvents other than those mentioned above may damage the polarizer.

Especially, do not use the following:

- Water
- Ketone
- Aromatic solvents
- 10.1.6 Do not attempt to disassemble the LCD Module.
- 10.1.7 If the logic circuit power is off, do not apply the input signals.
- 10.1.8 To prevent destruction of the elements by static electricity, be careful to maintain an optimum work environment.
 - a. Be sure to ground the body when handling the LCD Modules.
 - b. Tools required for assembly, such as soldering irons, must be properly ground.
 - c. To reduce the amount of static electricity generated, do not conduct assembly and other work under dry conditions.
 - d. The LCD Module is coated with a film to protect the display surface. Be care when peeling off this protective film since static electricity may be generated.



10.2 Storage precautions

- 10.2.1 When storing the LCD modules, avoid exposure to direct sunlight or to the light of fluorescent lamps.
- 10.2.2 The LCD modules should be stored under the storage temperature range. If the LCD modules will be stored for a long time, the recommend condition is:

Temperature : 0° C $\sim 40^{\circ}$ C

Relatively humidity: ≤80%

- 10.2.3 The LCD modules should be stored in the room without acid, alkali and harmful gas.
- 10.3 The LCD modules should be no falling and violent shocking during transportation, and also should avoid excessive press, water, damp and sunshine.